 Technical Data Sheet

ASSEMBLY MATERIALS

**Product Type:** Conductive Adhesive

**Product Name:** PC 3601

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**Description**

PC 3601 is a fast curing thermosetting, one-component, solvent-free, silver-filled epoxy conductive adhesive, designed for the connection of bare dies and SMT components on lead frames, foils and low cost substrates at low temperatures. The glues have a hardener system, which includes a cationic curing agent.

**Compliant Products**

- Conductive Adhesive: PC3200 Series
- Non-conductive Adhesive: NCA 6, NCA 11

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**Key Benefits**

- Fast curing system
- High electrical and thermal conductivity
- Low ionic contamination

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**Applications**

- Dispensing

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**Physical Properties**

<table>
<thead>
<tr>
<th>Processing Life (h)</th>
<th>Curing Profile</th>
<th>Substrate and Components</th>
</tr>
</thead>
<tbody>
<tr>
<td>Approx. 24</td>
<td>3 min / 90 °C</td>
<td>Flex PCB, foils and temp. sensitive substrates. Recommended surface: Ni/Au and Ag</td>
</tr>
<tr>
<td></td>
<td>5 min / 80 °C</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Adhesion (N/mm²)</th>
<th>Weight Loss during Curing Process at 150 °C (%)</th>
<th>Glass Transition Temperature (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Min. 8.5</td>
<td>Max. 0.1</td>
<td>Approx. 89</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Thermal Conductivity (W/mK)</th>
<th>Volume Resistivity (mΩ.cm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Min. 3</td>
<td>Max. 0.3</td>
</tr>
</tbody>
</table>

**Halogen Content**

- **Hydroylse Halogen**
  - Tolerance: Halogen < 50 ppm

**Cleaning Instructions**

The uncured adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. The cleaned parts must be completely dry before installing them in the machine. Defective components can be removed by heating the cured adhesive joint with hot air above 250°C. The hot remaining adhesive can be removed with a sharp tool.

**Adhesive Conditioning**

- Remove adhesive from freezer: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open jar/cartridge while adhesive is cold to prevent condensation
- Do not use faster defrost systems
Storage

- Store the adhesive in tightly-sealed containers and avoid exposure to high humidity and sunlight
- Store the cartridges with tip pointing downwards
- Max. expiration date: Shelf life: Please refer to the expiry date on the label of the packaged product
- Storage conditions in the freezer at –20 °C